

AMENDMENTS TO THE CLAIMS

Cancel claims 14 and 15 without prejudice.

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A method comprising:

picking up a clip with a chuck; and

while holding the clip with the chuck, picking up an integrated circuit (IC) die with the IC die in direct contact with the clip.

2. (original) The method of claim 1, wherein the picking up of the IC die includes applying a vacuum to the IC die.

3. (original) The method of claim 2, wherein the vacuum is applied to the IC die via an aperture in the clip.

4. (original) The method of claim 3, wherein the IC die is in contact with a polymer pad that is part of the clip.

5. (original) The method of claim 1, further comprising:

using the chuck to simultaneously place the clip and the IC die into juxtaposition with a heat spreader.

6. (original) The method of claim 5, further comprising:

releasing the clip and the IC die from the chuck while holding the IC die in place on the heat spreader with the clip.

7. (original) The method of claim 6, further comprising:

bonding the IC die to the heat spreader while holding the IC die in place on the heat spreader with the clip.

8. (original) The method of claim 7, further comprising:

after bonding the IC die to the heat spreader, removing the clip from the IC die and from the heat spreader.

9. (original) The method of claim 7, further comprising:

before bonding the IC die to the heat spreader, transporting the heat spreader with the IC die held in place on the heat spreader by the clip.

10. (original) The method of claim 9, wherein the transporting of the heat spreader with the IC die held thereon by the clip is performed after the releasing of the clip and the IC die from the chuck.

11. (original) The method of claim 7, wherein the bonding includes reflowing a solder layer on the heat spreader.

12. (original) The method of claim 1, further comprising:

using the chuck to simultaneously place the clip and the IC die into juxtaposition with a package substrate.

13. (canceled)

14-15. (canceled)

16. (currently amended) The method of claim 15, further comprising:

A method comprising:

holding a clip in a chuck such that an aperture in the clip is aligned with an aperture in the chuck;

picking up an integrated circuit (IC) die by applying a vacuum to the IC die via the apertures in the clip and in the chuck;

using the chuck to simultaneously place the clip and the IC die into juxtaposition with a heat spreader;

releasing the clip and the IC die from the chuck while holding the IC die in place on the heat spreader with the clip; and

bonding soldering the IC die to the heat spreader while holding the IC die in place on the heat spreader with the clip.

17. (currently amended) The method of claim 16, further comprising:

after bonding soldering the IC die to the heat spreader, removing the clip from the IC die and from the heat spreader.

18. (currently amended) The method of claim 14 16, wherein the IC die is held by the chuck with the clip interposed between the IC die and the chuck.

19-22. (canceled)

23. (previously presented) The method of claim 4, further comprising:

using the chuck to simultaneously place the clip and the IC die into juxtaposition with a heat spreader.